Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-10
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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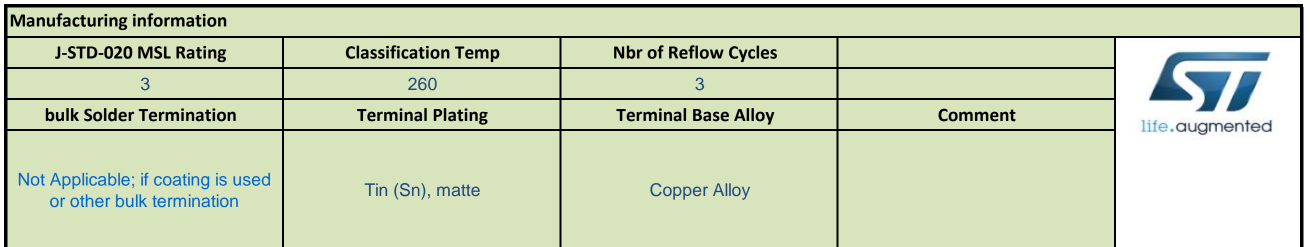
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32F767BIT6	P0UH*451XXXZ	A	9998	2017-04-10
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	2542.17	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
QFP	28x28x1.4	208	L Bend	
Comment	Package : UH LQFP 208 28x28x1.4 1.0 7147657			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH- 7th July 2017	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**TRUE**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P0UH*451XXXZ				7000000.0	0.0
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	24.661	mg	supplier	die	Silicon (Si)	7440-21-3		23.079	mg	935850	9078
				supplier	metallization	Aluminium (Al)	7429-90-5		0.111	mg	4501	44
				supplier	metallization	Copper (Cu)	7440-50-8		0.719	mg	29155	283
				supplier	metallization	Cobalt (Co)	7440-48-4		0.002	mg	81	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.100	mg	4055	39
				supplier	metallization	Tungsten (W)	7440-33-7		0.323	mg	13098	127
				supplier	Passivation	Silicon Nitride	12033-89-5		0.084	mg	3406	33
				supplier	Passivation	Silicon Oxide	7631-86-9		0.243	mg	9854	96
LEADFRAME (LGIC- C194)	M-011 Other inorganic materials	471.813	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		459.783	mg	974502	180862
				supplier	ALLOY	Iron (Fe)	7439-89-6		11.323	mg	23999	4454
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.566	mg	1199	223
				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.141	mg	299	56
LEADFRAME (LGIC- Ag)	M-011 Other inorganic materials	2.250	mg	supplier	COATING	Silver(Ag)	7440-22-4		2.250	mg	1000000	885
DIE ATTACH (Evertech -AP4200)	M-011 Other inorganic materials	2.842	mg	supplier	GLUE	Epoxy	9003-36-5		0.625	mg	219916	246
				supplier	GLUE	Silver(Ag)	7440-22-4		2.217	mg	780084	872
BONDING WIRE (Heraeus - HTS Au wi	M-011 Other inorganic materials	5.737	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		5.679	mg	989890	2234
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.058	mg	10110	23
ENCAPSULATION (Sumitomo -G631H(	M-011 Other inorganic materials	2023.517	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		206.951	mg	102068	81407
				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		1692.395	mg	836692	-334273
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		113.823	mg	56137	44774
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		10.348	mg	5104	4071
FINISHING- (ST380 -Sn)	M-011 Other inorganic materials	11.350	mg	supplier	EXTERNAL PLATING	Tin (Sn)	7440-31-5		11.350	mg	1000000	4465